Product data sheet

1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in an MLPAK33 (SOT8002) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Low threshold voltage
- Trench MOSFET technology
- MLPAK33 package (3.3 x 3.3 mm footprint)

3. Applications

- · High-side load switch
- Battery management
- DC-to-DC conversion
- Switching circuits

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C		-	-	-20	V
V_{GS}	gate-source voltage			-12	-	12	V
I _D	drain current	V _{GS} = -4.5 V; T _{amb} = 25 °C; t ≤ 5 s	[1]	-	-	-20.2	Α
Static charac	teristics		'	•	'		•
R _{DSon}	rociotanos	$V_{GS} = -4.5 \text{ V}; I_D = -12.3 \text{ A}; T_j = 25 \text{ °C}$		-	6.6	8.3	mΩ
		V_{GS} = -2.5 V; I_D = -9.7 A; T_j = 25 °C		-	9.6	13.3	mΩ

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².



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5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	1 2 3 4	
2	S	source		
3	S	source		
4	G	gate		
5	D	drain		
6	D	drain	Lanal	Ś 017aaa257
7	D	drain	8 7 6 5 MI DAK 22 (SOT 2002 4)	31.222
8	D	drain	MLPAK33 (SOT8002-1)	

6. Ordering information

Table 3. Ordering information

Type number	Package							
	Name	Description	Version					
PXP8R3-20QX		plastic thermal enhanced surface mounted package; mini leads; 8 terminals; pitch 0.65 mm; 3.3 x 3.3 x 0.8 mm body	SOT8002-1					

7. Marking

Table 4. Marking codes

Type number	Marking code
PXP8R3-20QX	9AW

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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C		-	-20	V
V _{GS}	gate-source voltage			-12	12	V
I _D	drain current	V _{GS} = -4.5 V; T _{amb} = 25 °C; t ≤ 5 s	[1]	-	-20.2	Α
		V _{GS} = -4.5 V; T _{amb} = 25 °C	[1]	-	-12.4	Α
		V _{GS} = -4.5 V; T _{amb} = 100 °C	[1]	-	-7.8	Α
		V _{GS} = -4.5 V; T _{sp} = 25 °C		-	-65.1	Α
I _{DM}	peak drain current	T_{amb} = 25 °C; single pulse; $t_p \le 10 \mu s$		-	-102.8	Α
P _{tot}	total power dissipation	T _{amb} = 25 °C; t ≤ 5 s	[1]	-	4.8	W
		T _{amb} = 25 °C	[1]	-	1.8	W
		T _{sp} = 25 °C		-	50	W
Tj	junction temperature			-55	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C
Source-drai	n diode		•		•	•
I _S	source current	T _{amb} = 25 °C	[1]	-	-1.7	Α

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².

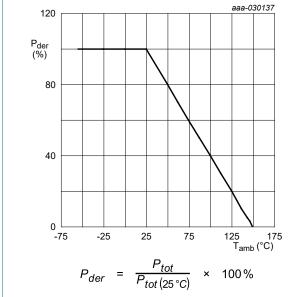


Fig. 1. Normalized total power dissipation as a function of ambient temperature

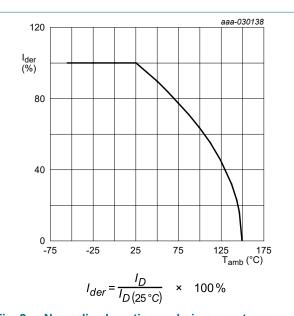


Fig. 2. Normalized continous drain current as a function of ambient temperature

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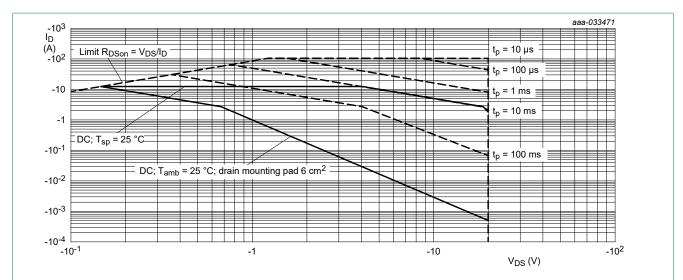


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

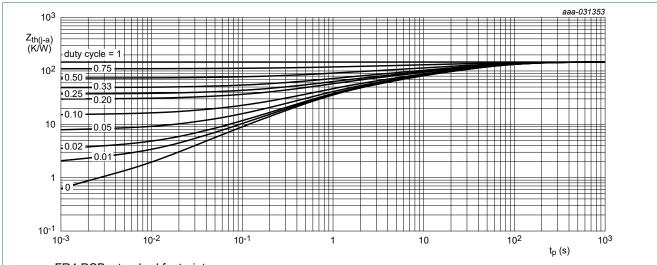
20 V, P-channel Trench MOSFET

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
ui(j-a)	thermal resistance from	in free air	[1]	-	145	185	K/W
	junction to ambient		[2]	-	55	70	K/W
		in free air; t ≤ 5 s	[2]	-	21	26	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point			-	1.5	2.5	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².



FR4 PCB, standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

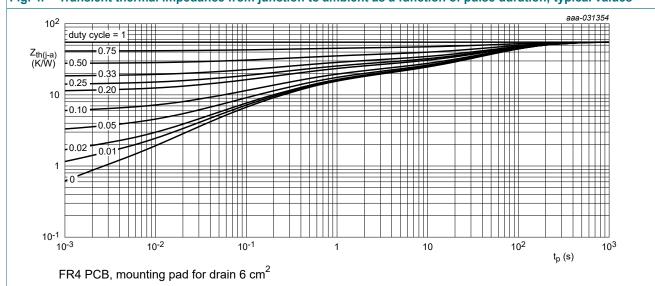


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

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10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	cteristics					
V _{(BR)DSS}	drain-source breakdown voltage	I_D = -250 μ A; V_{GS} = 0 V; T_j = 25 °C	-20	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = -250 \mu A; V_{DS} = V_{GS}; T_j = 25 \degree C$	-0.7	-0.9	-1.25	V
I _{DSS}	drain leakage current	V _{DS} = -20 V; V _{GS} = 0 V; T _j = 25 °C	-	-	-1	μA
I _{GSS}	gate leakage current	V _{GS} = -12 V; V _{DS} = 0 V; T _j = 25 °C	-	-	-0.1	μA
		V _{GS} = 12 V; V _{DS} = 0 V; T _j = 25 °C	-	-	0.1	μA
R _{DSon}	drain-source on-state	$V_{GS} = -4.5 \text{ V}; I_D = -12.3 \text{ A}; T_j = 25 ^{\circ}\text{C}$	-	6.6	8.3	mΩ
	resistance	V _{GS} = -4.5 V; I _D = -12.3 A; T _j = 150 °C	-	9.4	11.8	mΩ
		V_{GS} = -2.5 V; I_D = -9.7 A; T_j = 25 °C	-	9.6	13.3	mΩ
9fs	forward transconductance	V_{DS} = -10 V; I_D = -12.3 A; T_j = 25 °C	-	43	-	S
R _G	gate resistance	f = 1 MHz	-	2.4	-	Ω
Dynamic ch	aracteristics		1		1	
Q _{G(tot)}	total gate charge	V _{DS} = -10 V; I _D = -12.3 A; V _{GS} = -4.5 V;	-	61.2	91.8	nC
Q _{GS}	gate-source charge	T _j = 25 °C	-	10	-	nC
Q _{GS(th)}	pre-threshold gate- source charge		-	5.1	-	nC
Q _{GS(th-pl)}	post-threshold gate- source charge		-	4.9	-	nC
Q_{GD}	gate-drain charge		-	18.4	-	nC
V_{GSpl}	gate-source plateau voltage	V_{DS} = -10 V; I_D = -12.3 A; T_j = 25 °C	-	-1.7	-	V
C _{iss}	input capacitance	V _{DS} = -10 V; f = 1 MHz; V _{GS} = 0 V;	-	6200	-	pF
C _{oss}	output capacitance	T _j = 25 °C	-	840	-	pF
C _{rss}	reverse transfer capacitance		-	780	-	pF
t _{d(on)}	turn-on delay time	V _{DS} = -10 V; I _D = -9.7 A; V _{GS} = -4.5 V;	-	14	-	ns
t_r	rise time	$R_{G(ext)} = 5 \Omega; T_j = 25 °C$	-	42	-	ns
t _{d(off)}	turn-off delay time	1	-	101	-	ns
t _f	fall time	1	-	62	-	ns
Source-drai	n diode		1		1	
V _{SD}	source-drain voltage	$I_S = -1.7 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	-0.7	-1.2	V
t _{rr}	reverse recovery time	I _S = -1.7 A; dI _S /dt = 100 A/µs;	-	38	-	ns
Q _r	recovered charge	$V_{GS} = -4.5 \text{ V}; V_{DS} = -10 \text{ V}; T_j = 25 \text{ °C}$	-	26	-	nC
t _a	reverse recovery rise time	1	-	13	-	ns
t _b	reverse recovery fall	1	_	25		ns

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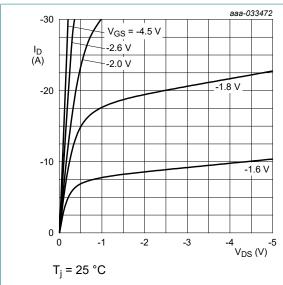


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

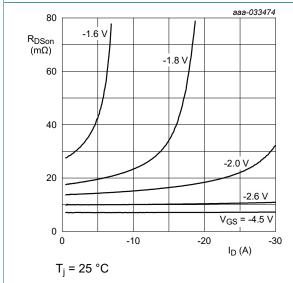


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

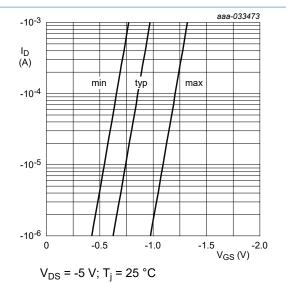


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

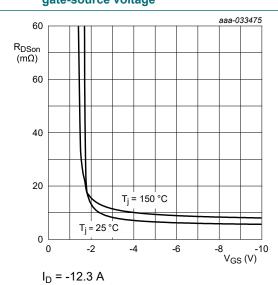


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

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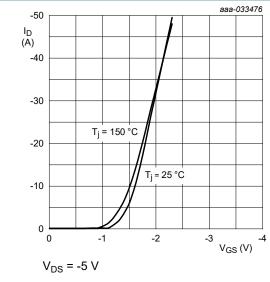


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

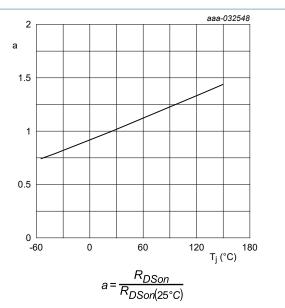


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

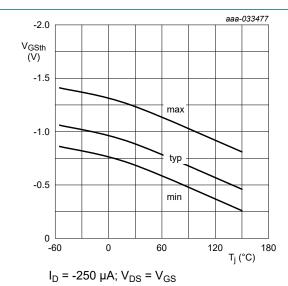


Fig. 12. Gate-source threshold voltage as a function of junction temperature

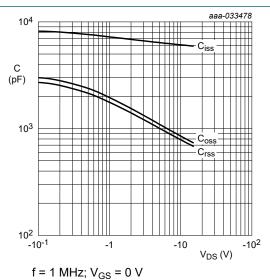


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical

values

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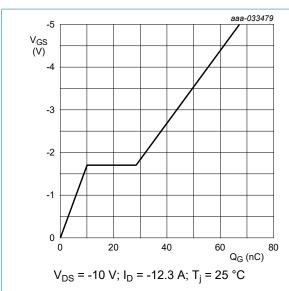


Fig. 14. Gate-source voltage as a function of gate charge; typical values

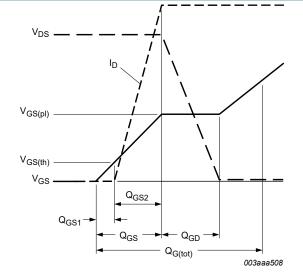


Fig. 15. Gate charge waveform definitions

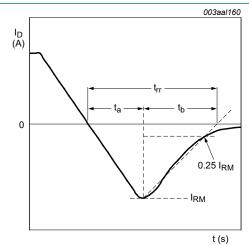


Fig. 16. Reverse recovery timing definition

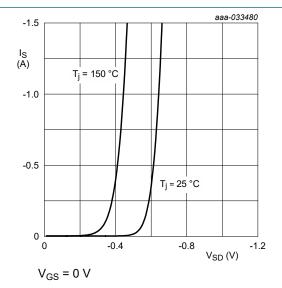
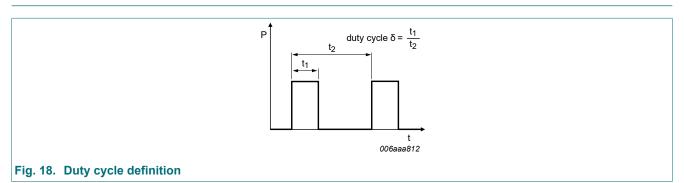


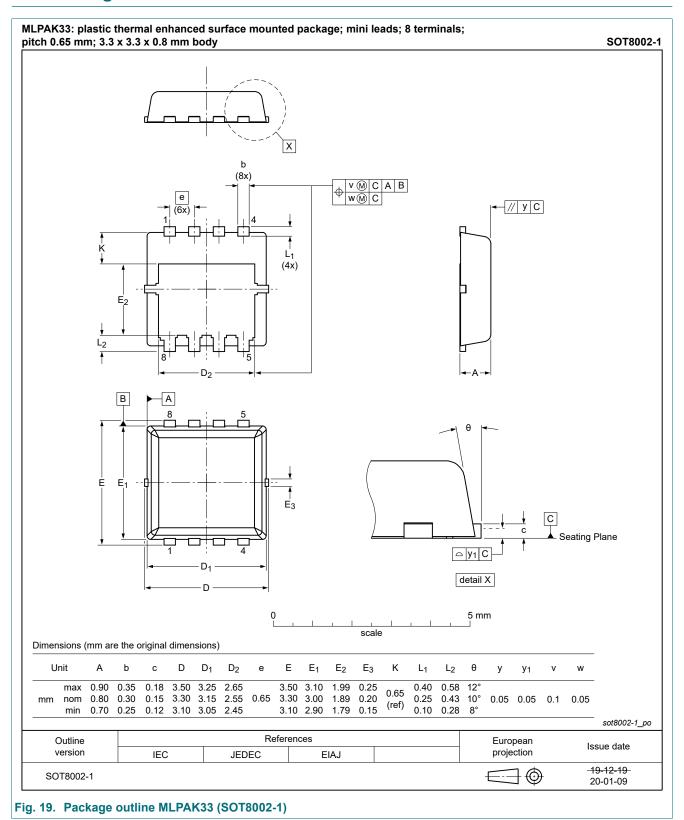
Fig. 17. Source current as a function of source-drain voltage; typical values

11. Test information



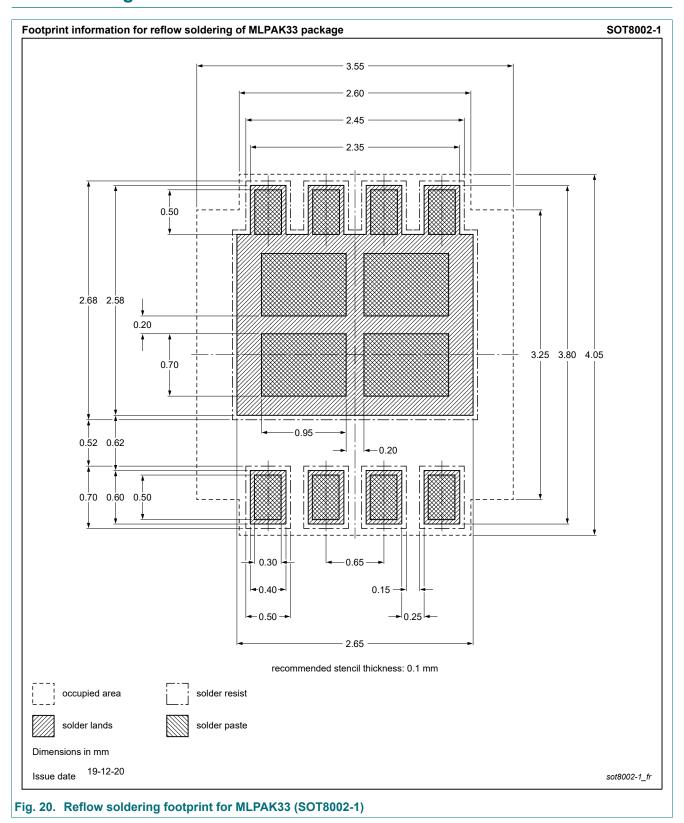
20 V, P-channel Trench MOSFET

12. Package outline



20 V, P-channel Trench MOSFET

13. Soldering



20 V, P-channel Trench MOSFET

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PXP8R3-20QX v.1	20210906	Product data sheet	-	-

20 V, P-channel Trench MOSFET

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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